



## Material Content Data Sheet



Halogen-Free

<b>Sales Product Name</b>	BSZ034N04LS	<b>Issued</b>	18. April 2021
<b>MA#</b>	MA005428995		
<b>Package</b>	PG-TSDSON-8-36	<b>Weight*</b>	35.48 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.447	1.26	1.26	12610	12610
leadframe	inorganic material	phosphorus	7723-14-0	0.004	0.01		103	
	non noble metal	zinc	7440-66-6	0.015	0.04		413	
	non noble metal	iron	7439-89-6	0.293	0.83		8263	
	non noble metal	copper	7440-50-8	11.903	33.55	34.43	335519	344298
wire	noble metal	gold	7440-57-5	0.028	0.08	0.08	790	790
encapsulation	organic material	carbon black	1333-86-4	0.035	0.10		986	
	plastics	epoxy resin	-	1.609	4.54		45350	
	inorganic material	silicondioxide	60676-86-0	15.844	44.65	49.29	446596	492932
leadfinish	non noble metal	tin	7440-31-5	0.420	1.19	1.19	11851	11851
plating	noble metal	silver	7440-22-4	0.003	0.01	0.01	89	89
solder	noble metal	silver	7440-22-4	0.017	0.05		481	
	non noble metal	tin	7440-31-5	0.034	0.10		961	
	non noble metal	lead	7439-92-1	0.631	1.78	1.93	17780	19222
heat sink clip	inorganic material	phosphorus	7723-14-0	0.001			35	
	non noble metal	zinc	7440-66-6	0.005	0.01		142	
	non noble metal	iron	7439-89-6	0.101	0.28		2837	
	non noble metal	copper	7440-50-8	4.087	11.52	11.81	115194	118208
*deviation	< 10%	Sum in total:				100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

Company	Infineon Technologies AG
Address	81726 Neubiberg
Internet	www.infineon.com